

Printed boards and printed board assemblies - Design and use - Part 6-4: Land pattern design - Generic requirements for dimensional drawings of surface mounted components (SMD) from the viewpoint of land pattern design

## EESTI STANDARDI EESSÕNA

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See Eesti standard EVS-EN IEC 61188-6-4:2019 sisaldab Euroopa standardi EN IEC 61188-6-4:2019 ingliskeelset teksti.	This Estonian standard EVS-EN IEC 61188-6-4:2019 consists of the English text of the European standard EN IEC 61188-6-4:2019.
Standard on jõustunud sellekohase teate avaldamisega EVS Teatajas	This standard has been endorsed with a notification published in the official bulletin of the Estonian Centre for Standardisation.
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ICS 31.180

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English Version

Printed boards and printed board assemblies - Design and use -  
Part 6-4: Land pattern design - Generic requirements for  
dimensional drawings of surface mounted components (SMD)  
from the viewpoint of land pattern design  
(IEC 61188-6-4:2019)

Cartes imprimées et cartes imprimées équipées -  
Conception et utilisation - Partie 6-4: Conception de la zone  
de report - Exigences génériques pour les dessins  
dimensionnels de composants montés en surface (CMS) du  
point de vue de la conception de la zone de report  
(IEC 61188-6-4:2019)

Leiterplatten und Flachbaugruppen - Konstruktion und  
Anwendung - Teil 6-4: Allgemeine Anforderungen an SMD-  
Maßzeichnungen hinsichtlich der Konstruktion des  
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(IEC 61188-6-4:2019)

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## European foreword

The text of document 91/1561/FDIS, future edition 1 of IEC 61188-6-4, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61188-6-4:2019.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2020-03-06
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2022-06-06

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In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60191-1	NOTE	Harmonized as EN IEC 60191-1
IEC 60191-6	NOTE	Harmonized as EN 60191-6
IEC 60191-6-1	NOTE	Harmonized as EN 60191-6-1
IEC 61188-5-1	NOTE	Harmonized as EN 61188-5-1
IEC 61188-5-2	NOTE	Harmonized as EN 61188-5-2
IEC 61188-5-3	NOTE	Harmonized as EN 61188-5-3
IEC 61188-5-4	NOTE	Harmonized as EN 61188-5-4
IEC 61188-5-5	NOTE	Harmonized as EN 61188-5-5
IEC 61188-5-6	NOTE	Harmonized as EN 61188-5-6
IEC 61188-5-8	NOTE	Harmonized as EN 61188-5-8
IEC 61191-1	NOTE	Harmonized as EN IEC 61191-1
IEC 61191-2	NOTE	Harmonized as EN 61191-2

**Normative references to international publications  
with their corresponding European publications**

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: [www.cenelec.eu](http://www.cenelec.eu).

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194	-	Terms and definitions for printed circuits	-	-
IEC 60194-2	-	Printed boards design, manufacture and assembly - Vocabulary - Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies	-	-

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

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**PRINTED BOARDS AND PRINTED BOARD ASSEMBLIES –  
DESIGN AND USE –**
**Part 6-4: Land pattern design – Generic requirements for dimensional  
drawings of surface mounted components (SMD) from the viewpoint of  
land pattern design**
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International Standard IEC 61188-6-4 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
91/1561/FDIS	91/1572/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.



A list of all parts in the IEC 61188 series, published under the general title *Printed boards and printed board assemblies – Design and use*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

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